

RoHS+Halogen Compliant Compliant

SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10B333KB8NFNC
- Description : CAP, 33nF, 50V, ±10%, X7R, 0603

A. Samsung Part Number

			<u>CL</u>	<u>10</u>	<u>B</u>	<u>333</u>	<u>K</u>	<u>B</u>	<u>8</u>	<u>N</u>	E	<u>N</u>	<u>C</u>			
			1	2	3	4	(5)	6	1	8	9	10	1			
1 Series		Samsu	na Mult	i-lave	r Cer	amic (Capa	citor								
② Size			(inch c	•			•	± 0.1		mm		W:	0.8 ± 0	.1	mm	
	4 a • •	V7D						•			•-		N I:			
③ Dieleo	tric	X7R					(8)	Inne	r eie	ctroc	le		Ni			
4 Capac	itance	33	nF					Tern	ninat	tion			Cu			
5 Capac	itance	±10	%					Plati	ng				Sn 100%		(Pb Free	e)
tolera	nce						9	Proc	luct				Product fo	r PC	OWER ap	oplication
6 Rated	Voltage	50	V				10	Spee	cial				Reserved	for f	future use	e
⑦ Thick	ness	0.8	± 0.1	mm			1	Pack	cagir	ng			Cardboard	d Ty	pe, 7" ree	el

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1klz±10% 1.0±0.2Vrms						
Tan δ (DF)	0.025 max.							
Insulation	10,000Mohm or 500Mohm · <i>µ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X7R							
Characterisitcs	(From -55 $^{\circ}$ to 125 $^{\circ}$ C, Capacitance change shoud be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours \times 3 direction (x, y, z)
Moisture	Capacitance change : within ±12.5%	With rated voltage
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR : 500Mohm or 25Mohm $\cdot \mu F$	
	Whichever is Smaller	
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage
Resistance	Tan δ : 0.05 max	Max. operating temperature
	IR : 1000Mohm or 50Mohm · μF	
	Whichever is Smaller	1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C
		\rightarrow Max. operating temperature \rightarrow 25 °C
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.